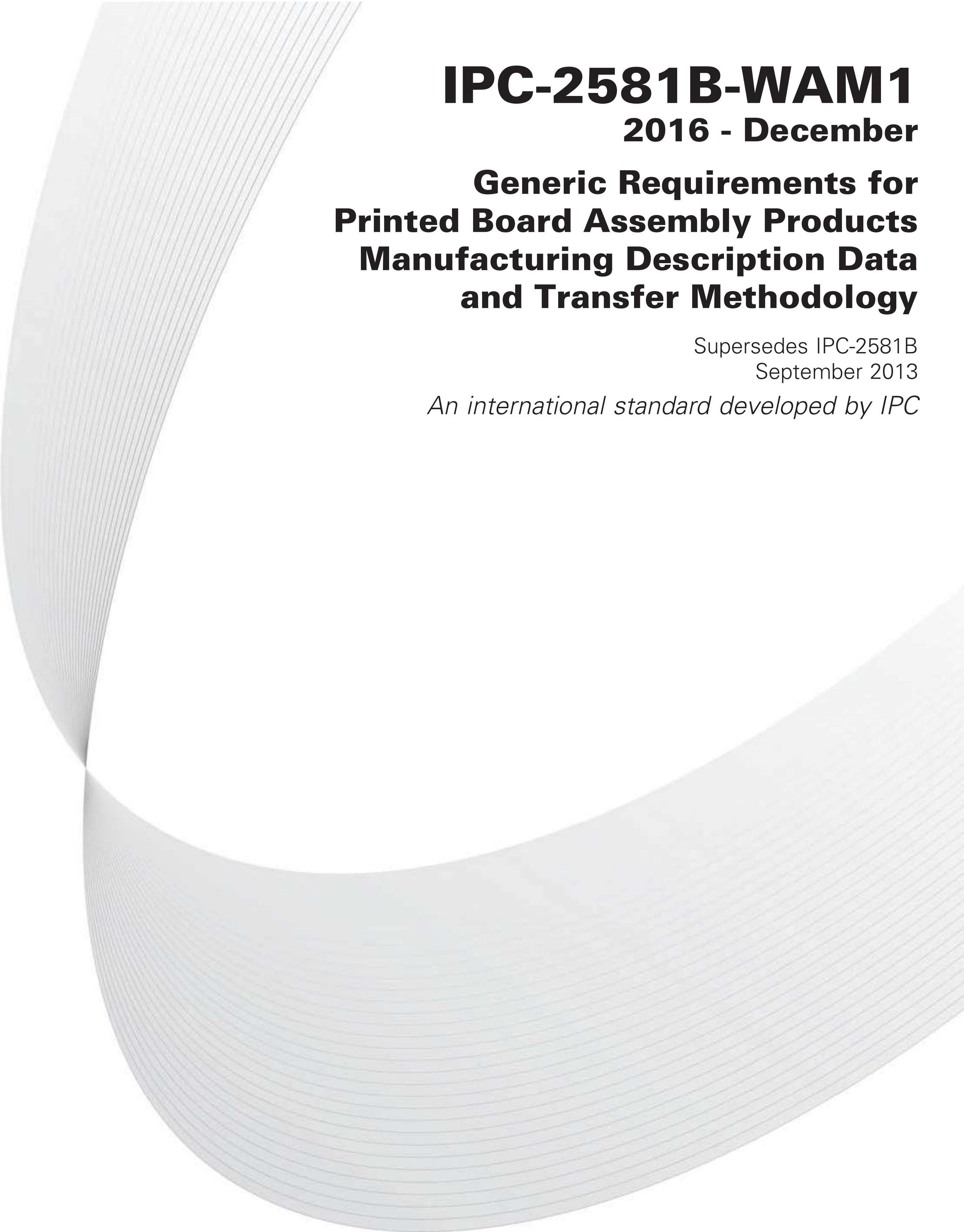

IPC-2581B-WAM1

2016 - December

Generic Requirements for Printed Board Assembly Products Manufacturing Description Data and Transfer Methodology

Supersedes IPC-2581B
September 2013

An international standard developed by IPC

Association Connecting Electronics Industries

IPC®

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- Minimize time to market
- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feedback system on use and problems for future improvement

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- Keep people out
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IPC-2581B-WAM1

Generic Requirements for Printed Board Assembly Products Manufacturing Description Data and Transfer Methodology

Developed by Product Data Description (Laminar View) Subcommittee (2-16) of the Electronic Product Data Description Committee (2-10) of IPC

Supersedes:

IPC-2581B - September 2013
IPC-2581A - May 2012
IPC-2581 with Amendment 1 - May 2007
IPC-2581 - March 2004

Contact:

IPC
3000 Lakeside Drive, Suite 105N
Bannockburn, Illinois
60015-1249
Tel 847 615.7100
Fax 847 615.7105

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Acknowledgment

Any document involving a complex technology draws material from a vast number of sources across many continents. While the principal members of the Product Data Description (Laminar View) Subcommittee (2-16) of the Electronic Product Data Description Committee (2-10) are shown below, it is not possible to include all of those who assisted in the evolution of this standard. To each of them, the members of the IPC extend their gratitude.

Electronic Product Data Description Committee	**Product Data Description (Laminar View) Subcommittee**	**Technical Liaison of the IPC Board of Directors**
Chair	Chair	
Gary M. Ferrari	Karen McConnell	Bob Neves
FTG Circuits	Northrop Grumman Corporation	Microtek (Changzhou) Laboratories

Product Data Description (Laminar View) Subcommittee

Edward Acheson, Cadence Design Systems Inc.

Craig Armenti, Zuken USA, Inc.

Kjell Asp, Ericsson AB

Jimmy Baccam, Lockheed Martin Missiles & Fire Control

Robert Bagsby, Rockwell Collins

Tomas Bergsten, Ericsson AB

Gary Carter

Max Clark, Mentor Graphics Corporation

Joseph Clark, DownStream Technologies, LLC

Amy Clements, Zuken USA, Inc.

Larry Frost, Sanmina Corporation

Terry Hoffman, Cisco Systems Inc.

Satoshi Kojima, NEC Solution Innovators, Ltd.

Ronny Kovartovsky, Frontline PCB Solutions

Kevin Kusiak, Lockheed Martin Space Systems Company

Jeff Lewis, Holaday Circuits Inc.

Humair Mandavia, Zuken USA, Inc.

Jason Marsh, Nextflex

Karen McConnell, Northrop Grumman Corporation

Kristopher Moyer, Aerojet Rocketdyne

William Newhard, DownStream Technologies, LLC

Sheldon Parnes, Ansys

James Pierce, Axiom Electronics, LLC

Hemant Shah, Cadence Design Systems Inc.

Chris Shaw, Fujitsu Network Communications

Rainer Taube, Taube Electronic GmbH

Karel Tavernier, Ucamco

Denise Turley, Fujitsu Network Communications

John Vaughn, Fujitsu Network Communications

Wenju Wang, Cadence Design Systems Inc.

Steve Watt, Zuken USA, Inc.

Jamie Wise, WISE Software Solutions Inc.

A special note of thanks goes to the following individuals for their dedication to bringing this project to fruition. We would like to highlight those individuals who made major contributions to the development of this standard.

Edward Acheson, Cadence Design Systems Inc.

Kent Balius, TTM Technologies

Tomas Bergsten, Ericsson AB

Gary Carter

Joseph Clark, DownStream Technologies, LLC

Terry Hoffman, Cisco Systems Inc.

Ronny Kovartovsky, Frontline PCB Solutions

Humair Mandavia, Zuken USA, Inc.

William Newhard, DownStream Technologies, LLC

James Pierce, Axiom Electronics, LLC

Hemant Shah, Cadence Design Systems Inc.

Chris Shaw, Fujitsu Network Communications

John Vaughn, Fujitsu Network Communications

Steve Watt, Zuken USA, Inc.

Jamie Wise, WISE Software Solutions Inc.

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TABLE OF CONTENTS

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